

## SMB Plastic-Encapsulate Diodes

### General Purpose Rectifier Diodes

#### Features:

- $I_{F(AV)}$  5A
- $V_{RRM}$  50V-1000V
- High surge current capability
- Polarity: Color band denotes cathode

#### Applications:

- Rectifier

#### Marking

- S5X

X : From A To M

SMB



#### Limiting Values(Absolute Maximum Rating)

Item	Symbol	Unit	Test Conditions	S5						
				A	B	D	G	J	K	M
Repetitive Peak Reverse Voltage	$V_{RRM}$	V		50	100	200	400	600	800	1000
Maximum RMS Voltage	$V_{RMS}$	V		35	70	140	280	420	560	700
Average Forward Current	$I_{F(AV)}$	A	60Hz Half-sine wave , Resistance load , $T_L=110^{\circ}C$	5.0						
Surge(Non-repetitive)Forward Current	$I_{FSM}$	A	60Hz Half-sine wave , 1 cycle , $T_a=25^{\circ}C$	150						
Operation Junction and Storage Temperature Range	$T_J, T_{STG}$	$^{\circ}C$		-55 ~ +150						

#### Electrical Characteristics ( $T=25^{\circ}C$ Unless otherwise specified)

Item	Symbol	Unit	Test Condition	S5					
				A	B	D	G	J	K
Peak Forward Voltage	$V_F$	V	$I_F=5.0A$	1.15					
Peak Reverse Current	$I_{RRM1}$	$\mu A$	$V_{RM}=V_{RRM}$	$T_a=25^{\circ}C$					
	$I_{RRM2}$			$T_a=125^{\circ}C$					
Thermal Resistance(Typical)	$R_{\theta J-A}$	$^{\circ}C/W$	Between junction and ambient	47					
	$R_{\theta J-L}$		Between junction and terminal	13					

#### Notes:

Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.30" x 0.30" (8.0 mm x 8.0 mm) copper pad areas

**Typical Characteristics**

FIG.1: FORWARD CURRENT DERATING CURVE

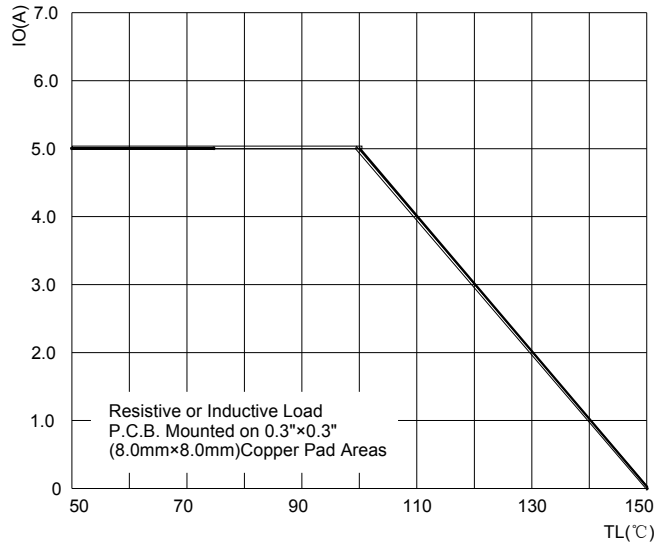


FIG.2: MAXIMUM NON-REPETITIVE FORWARD URGE CURRENT

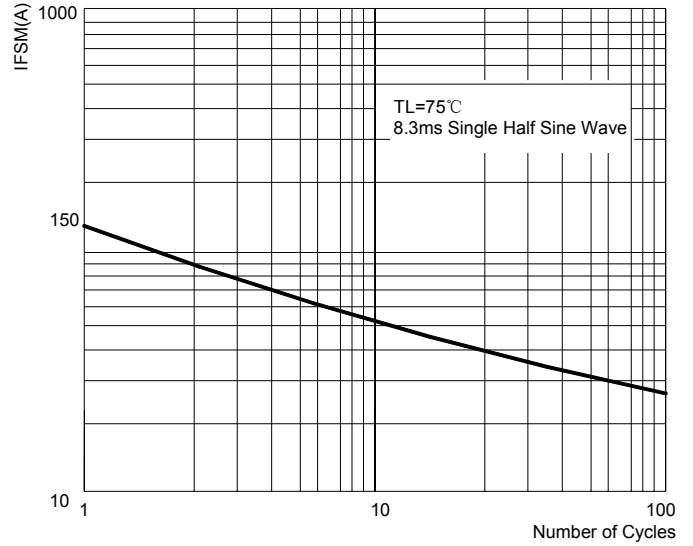


FIG.3: TYPICAL FORWARD CHARACTERISTICS

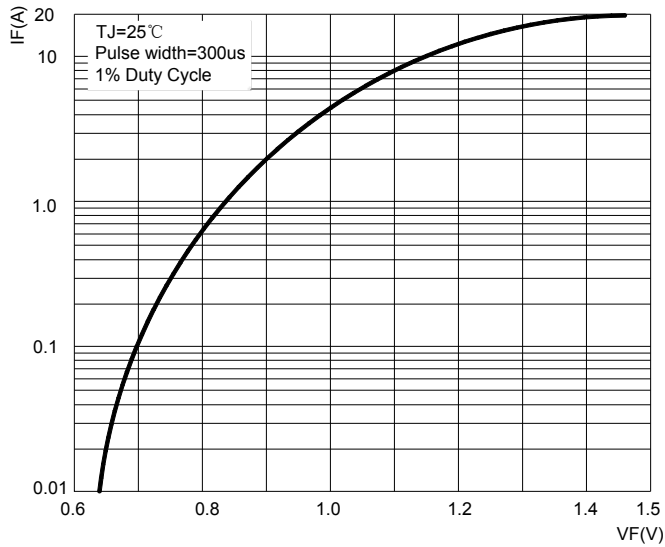
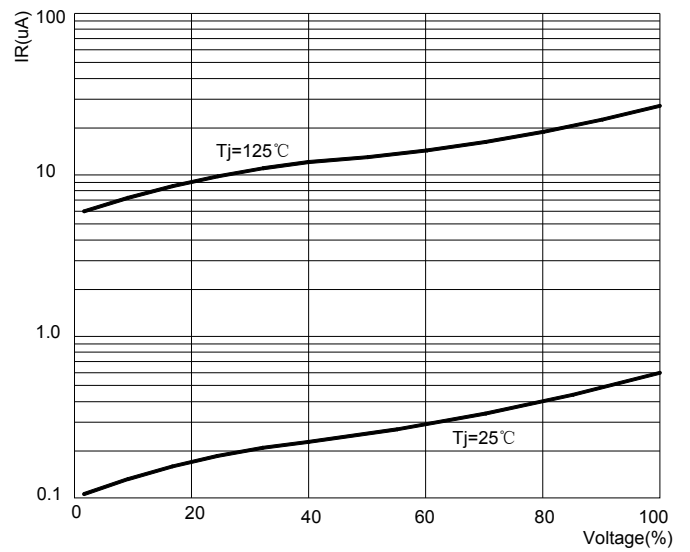
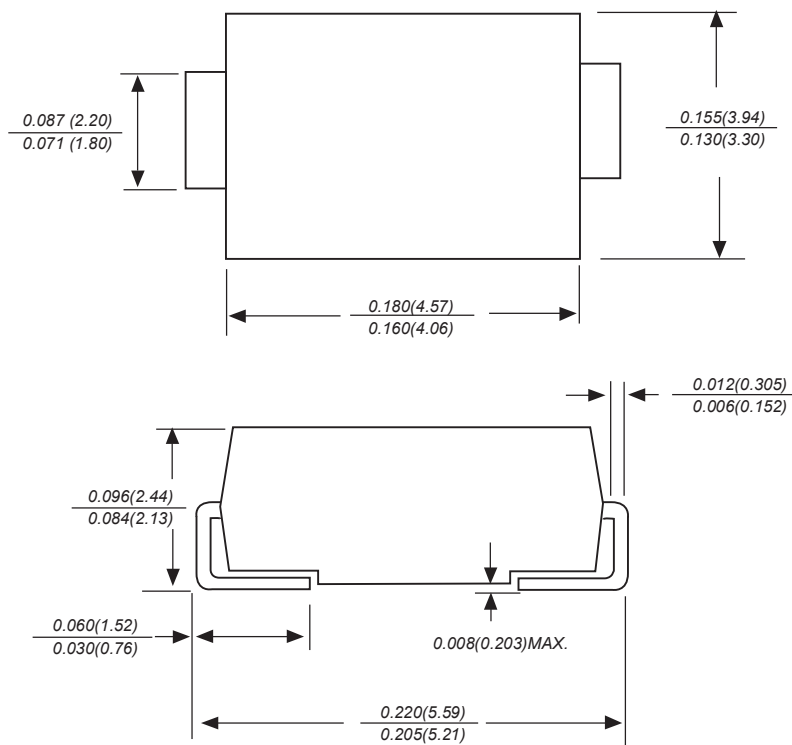


FIG.4: TYPICAL REVERSE CHARACTERISTICS

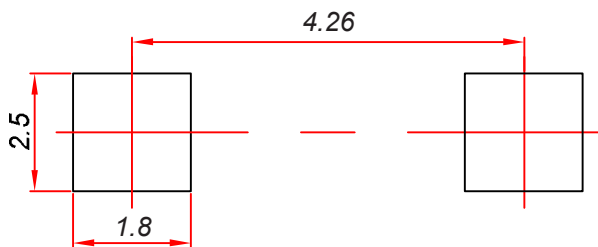


### SMB Package Outline Dimensions



Dimensions in inches and (millimeters)

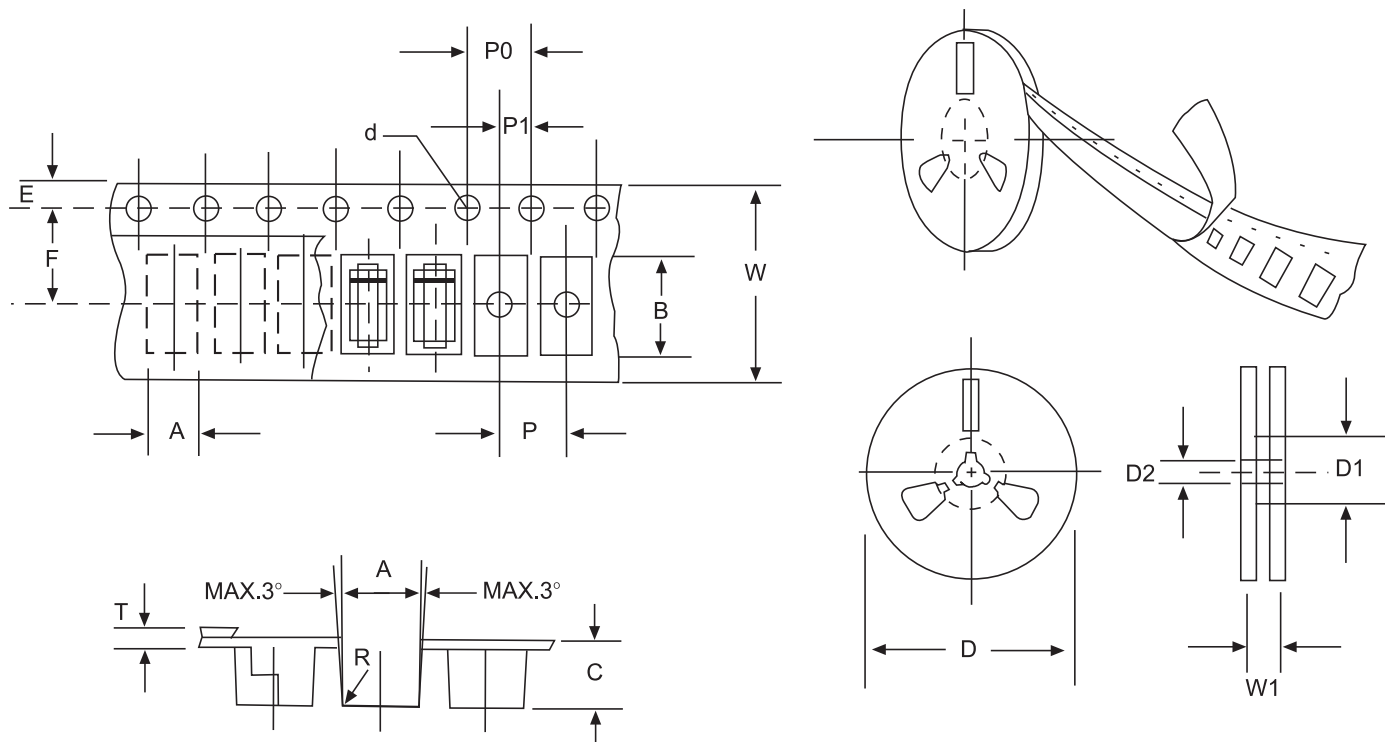
### SMB Suggested Pad Layout



**Note:**

1. Controlling dimension: in millimeters.
2. General tolerance:  $\pm 0.05mm$ .
3. The pad layout is for reference purposes only.

## Reel Taping Specifications For Surface Mount Devices-SMB



**FIG: CONFIGURATION OF SURFACE MOUNTED DEVICES TAPING**

ITEM	SYMBOL	SMBG mm(inch)
Carrier width	A	4.09±0.1(0.161±0.004)
Carrier length	B	5.82±0.1(0.229±0.004)
Carrier depth	C	2.50±0.1(0.100±0.004)
Sprocket hole	d	1.55±0.05(0.061±0.002)
Reel outside diameter	D	330±2.0(13±0.079)
Reel inner diameter	D1	75±1.0 ( 2.95 ±0.039)
Feed hole diameter	D2	13±0.5(0.512±0.020)
Sprocket hole position	E	1.75±0.1(0.069±0.004)
Punch hole position	F	5.65±0.05(0.222±0.002)
Punch hole pitch	P	8.0±0.1(0.315±0.004)
Sprocket hole pitch	P0	4.0±0.1(0.157±0.004)
Embossment center	P1	2.0±0.1(0.079±0.004)
Total tape thickness	T	0.32±0.1(0.013±0.004)
Tape width	W	12.0±0.2(0.472±0.008)
Reel width	W1	16.8±2.0(0.661±0.079)

NOTE: Devices are packed in accordance with EIA standard RS-481-A and specification given above.